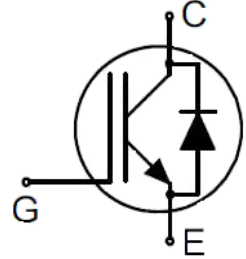


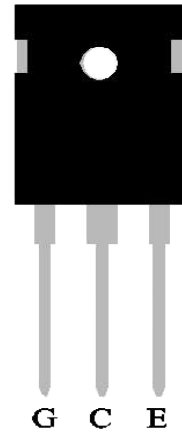
Features

- Offers high breakdown voltage to 1350V for improved reliability
- Powerful monolithic body diode with low forward voltage designed for soft commutation only
- Very tight parameter distribution
- High ruggedness, temperature stable behavior
- Low V_{CEsat}
- Easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Qualified according to JESD-022 for target applications



Applications

- Inductive cooking
- Inverterized microwave ovens
- Resonant converters
- Soft switching applications



Package pin definition

- Pin 1 -- Gate
- Pin 2 & Backside -- Collector
- Pin 3 -- Emitter

Package Marking and Ordering Information

Part #	V_{ce}	I_c	$V_{cesat}, T_{vj}=25^{\circ}C$	T_{vjmax}	Package	Marking
IHW20N135R5F	1350V	20A	1.7V	175	TO-247-3	20PR5F

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emmitter voltage	V_{CE}	1350	V
CD collector current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_C	40.0 20.0	A
Pulsed collector current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{C\ pulse}$	60.0	A
Non repetitive peak collector current ¹⁾	I_{CSM}	200.0	A
Turn off safe operating area $V_{CE} \leq 1350\text{V}$, $T_{vj} \leq 175^\circ\text{C}$	-	60.0	A
Diode forward current $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	I_F	40.0 20.0	A
Diode pulsed current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{F\ pulse}$	60.0	A
Gate-emitter voltage	V_{GE}	± 20	V
Power dissipation $T_c = 25^\circ\text{C}$ Power dissipation $T_c = 100^\circ\text{C}$	P_{tot}	333 167	W
Operating junction and storage temperature	T_j, T_{stg}	-40...+175	$^\circ\text{C}$
Soldering temperature, wave soldering 1.6mm (0.063in.) form case for 10s		260	$^\circ\text{C}$
Mounting torque, M3 Screw Maximum of mounting porcesses:3	M	0.6	Nm

Thermal Resistance

Parameter	Symbol	Value	Unit
IGBT thermal resistance, junction case. Max	R_{thJC}	0.45	$^\circ\text{C}/\text{W}$
Diode thermal resistance, junction case. Max	R_{thJC}	0.45	
Thermal resistance, junction – ambient. Max	R_{thJA}	40	

¹⁾ capacitor charging saturation current limited by $T_{vjmax} < 175^\circ\text{C}$ and $t_p < 3\mu\text{s}$

Electrical Characteristic (at T_J = 25 °C, unless otherwise specified)

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

Static Characteristic

Collector-emitter breakdown voltage	V _{(BR)CES}	V _{GE} = 0V, I _C = 0.5mA	1350	-	-	V
Collector-emitter saturation voltage	V _{CEsat}	V _{GE} = 15.0V, I _C = 20A	-	1.70	1.85	V
		T _{vj} = 25°C	-	1.79	-	
		T _{vj} = 125°C	-	1.90	-	
Diode forward voltage	V _F	V _{GE} = 0V, I _F = 20A	-	1.15	1.50	V
		T _{vj} = 25°C	-	1.05	-	
		T _{vj} = 125°C	-	1.00	-	
Gate-emitter threshold voltage	V _{GE(th)}	V _{GE} = V _{CE} , I _C = 1mA	4.8	-	6.8	V
Zero gate voltage collector current	I _{CES}	V _{CE} = 1350V, V _{GE} = 0V	-	-	100.0	μA
		T _{vj} = 25°C	-	400.0	-	
Gate-emitter leakage current	I _{GES}	V _{CE} = 0V, V _{GE} = 20V	-	-	100.0	nA
Transconductance	g _{fs}	V _{CE} = 20V, I _{CE} = 20A	-	15.0	-	S

Dynamic Characteristic

Input Capacitance	C _{ies}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz	-	1781	-	pF
Output Capacitance	C _{oes}		-	95	-	
Reverse Transfer Capacitance	C _{res}		-	57	-	
Gate Total Charge	Q _G	V _{CC} = 1080V, I _C = 20A, V _{GE} = 15V	-	175	-	nC
Gate-Source charge	Q _{gs}		-	14	-	
Gate-Drain charge	Q _{gd}		-	110	-	
Turn-off delay time	t _{d(off)}	T _{vj} = 25°C, V _{CC} = 600V, I _C = 20A, V _{GE} = 0.0/15.0V, R _G = 10.0Ω	-	204	-	ns
Fall time	t _f		-	132	-	
Turn-off energy	E _{off}		-	1.02	-	

Electrical Characteristic (at T_j = 25 °C, unless otherwise specified)

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Turn-off delay time	$t_{d(off)}$	T _{vj} = 175°C, V _{CC} = 600V, I _C = 20A, V _{GE} = 0.0/15.0V, R _G = 10.0Ω	-	230	-	ns
Fall time	t_f		-	190	-	
Turn-off energy	E _{off}		-	1.30	-	mj

Typical Performance Characteristics

Figure 1. Safe operating area
($D=0, T_C=25^\circ\text{C}, T_{vj}=175^\circ\text{C}; V_{GE}=15\text{V}, t_p=1\mu\text{s}$)

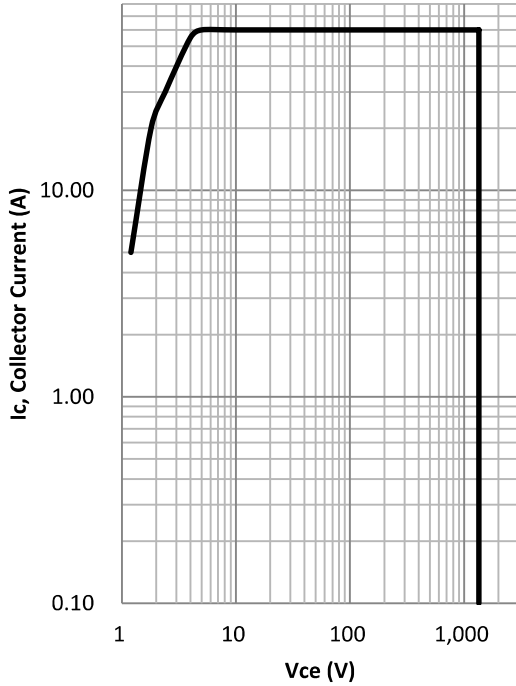


Figure 2. Power dissipation as a function of case temperature ($T_{vj}\leq 175^\circ\text{C}$)

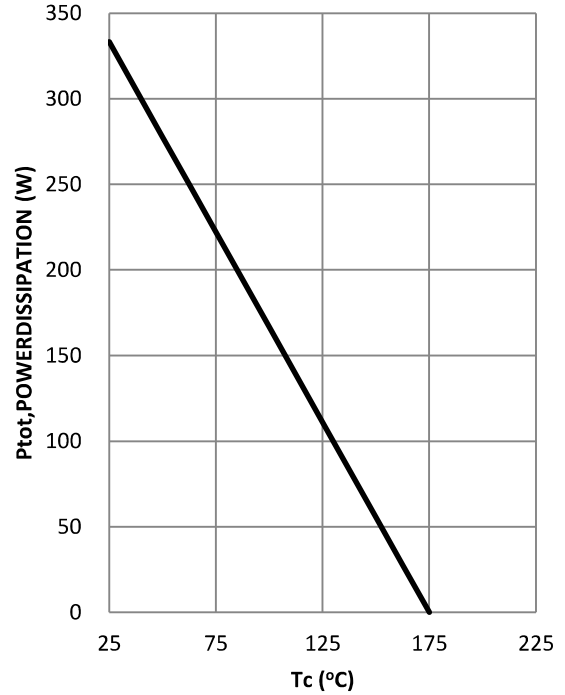


Fig 3: Typical switching time Vs IC Characteristics ($T_C=25^\circ\text{C}$)

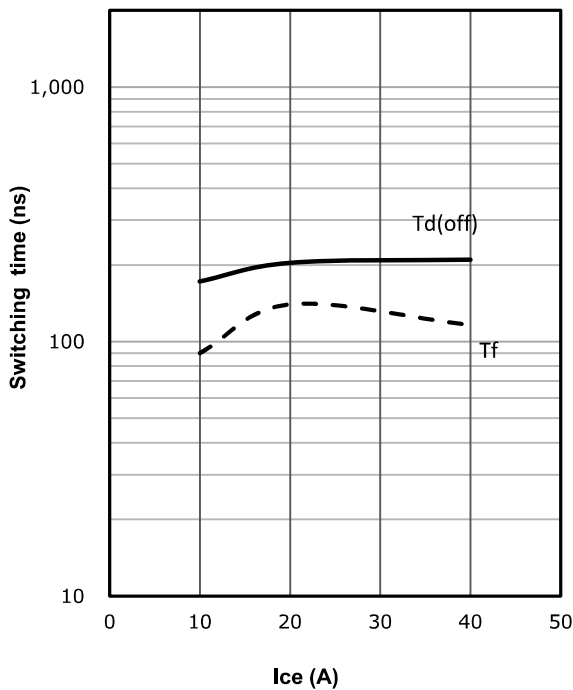


Fig 4: Typical switching Energy Vs IC Characteristics ($T_C=25^\circ\text{C}$)

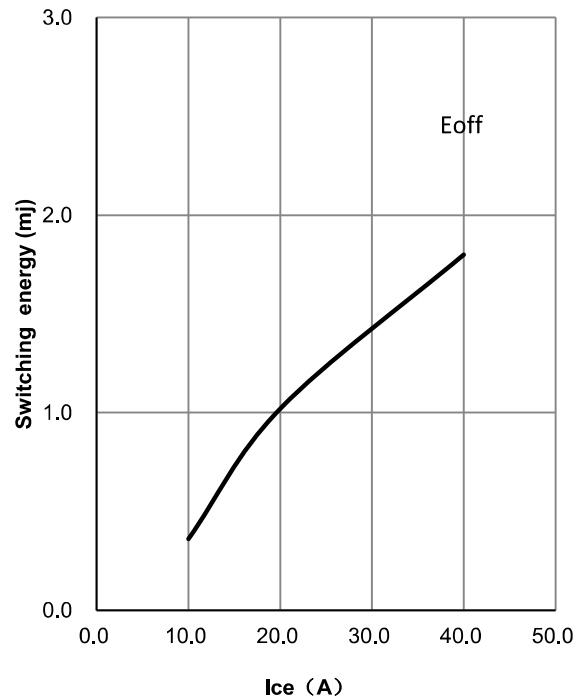


Fig 5: Transfer Characteristics

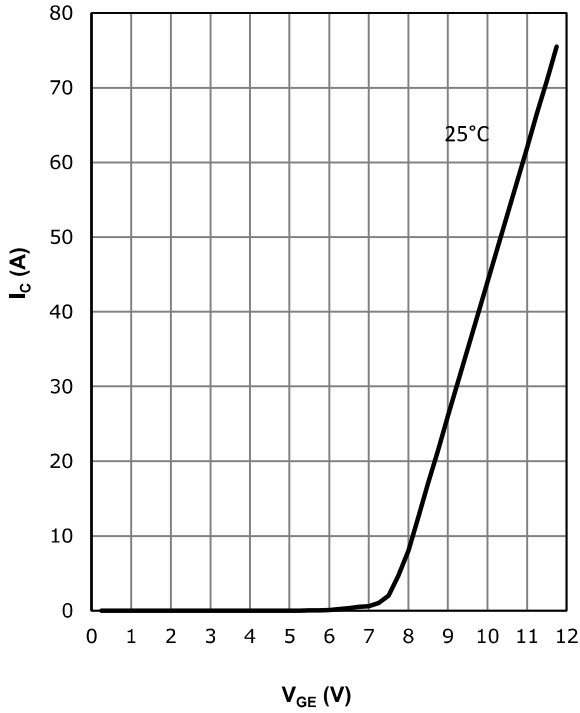


Fig 6: Capacitance Characteristics

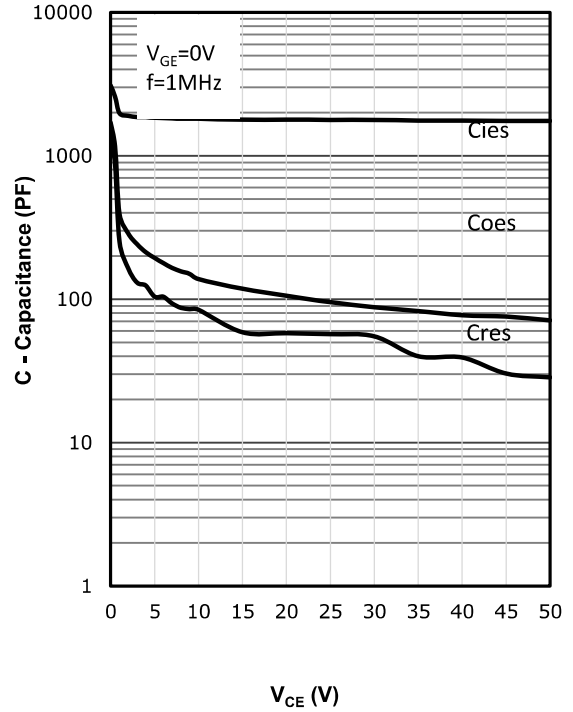


Fig 7: Gate Charge Characteristics

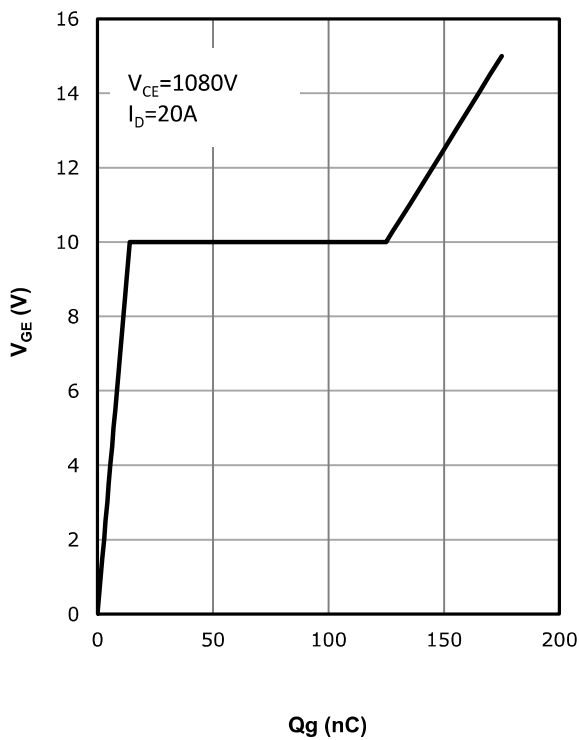
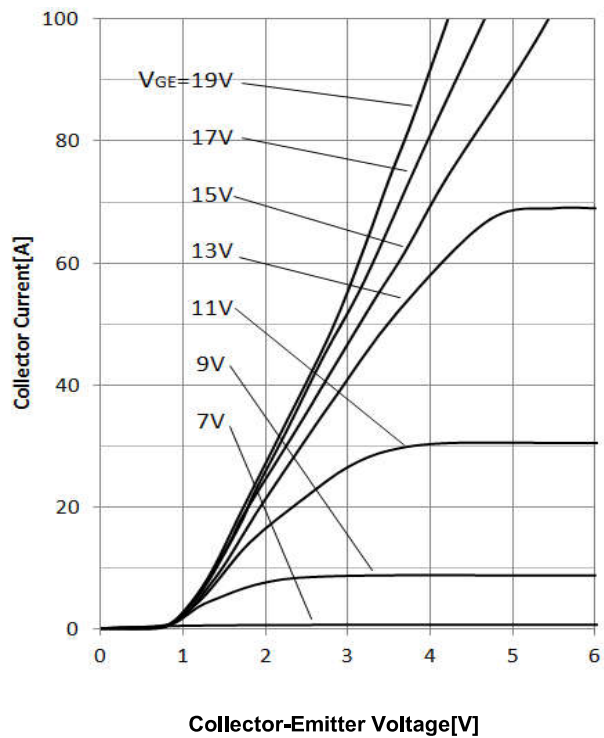
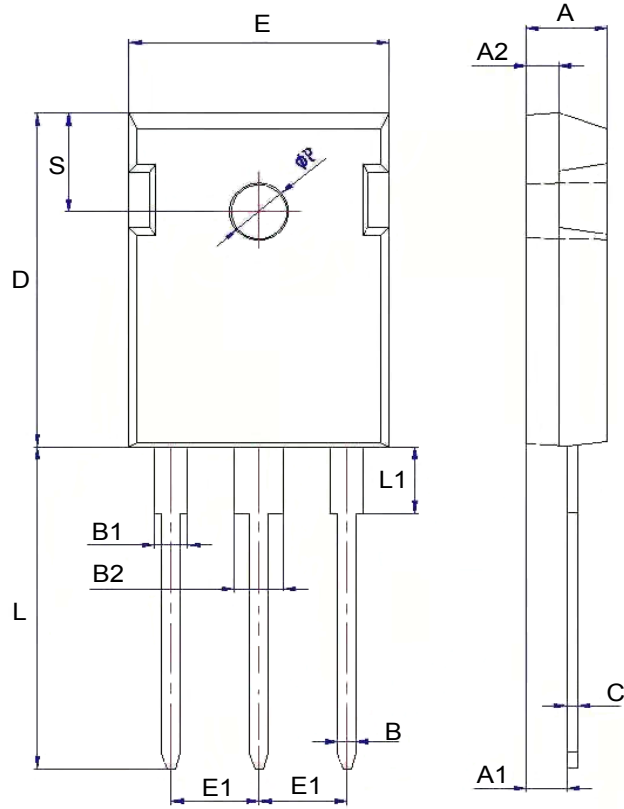


Fig 8. Typical output characteristic($T_c=25^\circ\text{C}$)



Package Dimensions

Package TO-247-3



Symbol	Dimensions In Millimeters	
	Min	Max
A	4.70	5.30
A1	2.30	2.70
A2	1.70	2.30
B	1.00	1.30
B1	1.80	2.20
B2	2.80	3.20
C	0.55	0.75
D	20.70	21.30
E	15.70	16.30
E1	5.15	5.75
L	19.80	20.80
L1	4.00	4.40
S	6.05	6.35
P	3.30	3.80

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